

## SPECIFICATIONS

CUSTOMER	:
SAMPLE CODE	: SH102600T009-IBC07
MASS PRODUCTION CODE	PH102600T009-IBC07
SAMPLE VERSION	<u>·</u> 01
SPECIFICATIONS EDITION	. 005
DRAWING NO. (Ver.)	LMD-PH102600T009-IBC07 (Ver.002)
PACKAGING NO. (Ver.)	PKG-PH102600T009-IBC07 (Ver.001)

## **Customer Approved**

Date:

	Approved	Checked	Designer					
(	黃秋源 Dliver Huang	石建莊 Stone Shin	王聖硯 Stephen Wang					
	<ul> <li>Preliminary specification for design input</li> <li>Specification for sample approval</li> </ul>							
	Р	OWERTIP TECH. CORP.						
Headquarters	<ul> <li>No.8, 6<sup>th</sup> Road, Taichung In</li> <li>Taichung, Taiwan</li> </ul>	dustrial Park, TEL: 886-4-2355-8168 FAX: 886-4-2355-8166						



## History of Version

Date	Ver.	Edi.	Description	Page	Design by
11/22/2017	01	001	New Drawing	-	Stephen
02/23/2018	01	002	New Sample	-	Stephen
03/20/2018	01	003	Modify Spec (Page 5,10)	-	Stephen
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## **1. SPECIFICATIONS**

### 1.1 Features

Item	Standard Value
Display Resolution	1024 *3 (RGB) * 600 Dots
LCD Type	a-Si TFT , Normally White , Transmissive Type
Touch Panel	Projective Capacitive Touch Panel USB HID Touch
Screen Size(inch)	7.0 inch
Eyes Viewing Direction	12 O'clock
Grayscale Inversion Direction	6 O'clock
LCD Surface Treatment	Anti-Glare
Color Configuration	R.G.B. Vertical Stripe
Backlight Type	White LED B/L
Weight	199.1 g
Interface	HDMI
Controller/Driver IC	HYCON 4635
ROHS	THIS PRODUCT CONFORMS THE ROHS OF PTC Detail information please refer website : http://www.powertip.com.tw/news_detail.php?Key=1&cID=1

# 1.2 Mechanical Specifications

Active Area

Item	Standard Value			
Outline Dimension	164.9 (W) * 100.0 (L) * 15.7 (H)	mm		
LCD panel				

154.21 (W) \* 85.92 (L)

Note : For detailed information please refer to LCM drawing.

mm



## **1.3 Absolute Maximum Ratings**

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply for Digital Circuit	VBus	GND=0V	-0.3	+6.0	V
Logic Supply Voltage	DVDD	-	-0.5	5	V
Analog Supply Voltage	AVDD	-	-0.5	15	V
Low Supply Voltage	VGL	-	-20	0.3	V
High Supply Voltage	VGH	-	-0.3	42	V
Operating Temperature	TOP (Ts)	Note 1	-20	+70	°C
Storage Temperature	Тѕт (Та)	Note 2	-30	+80	°C

Note 1 : Ts is the temperature of panel's surface

Note 2 : Ta is the ambient temperature of samples

### **1.4 DC Electrical Characteristics**

Module					GND	= 0V, Ta = 25°C
Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Input Signal Voltage	VBus	4.75	5.0	5.25	V	-
Supply Current	IVBus	650	750	950	mA	Pattern = Full Display
Input Signal Voltage	VCOM	3.3	3.8	4.3	V	-
Logic Supply Voltage	DVDD	2.5	3.3	3.6	V	-
Analog Supply Voltage	AVDD	8.0	11.0	13.5	V	-
Low Supply Voltage	VGL	-7.1	-6.8	-6.5	V	-
High Supply Voltage	VGH	19.7	20.0	20.3	V	-
	VIH	0.7*DVDD	-	DVDD	V	-
Logic Input Voltage	VIL	GND	-	0.3*DVDD	V	-

Note1: The customer has to check the input current is greater than 1.5A.

Note2: Supply voltage which is included backlight drive.

Note3: Maximum current for RGB screen is 735~750mA (Full Display).

Note4: We use advised USB 2.0/3.0 Y-cable to power supply.



## **1.5 Optical Characteristics**

### TFT LCD Module

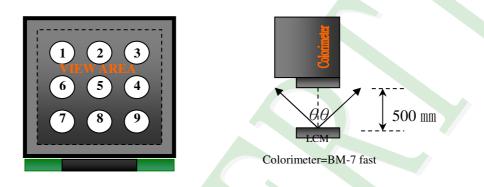
Ta=25°C

								a=23 0	
ltem	Item		Condition	Min.	Тур.	Max.	unit		
Doopopoo Timo	Rise	Tr	Ta = 25°C	-	10	20		Note 2	
Response Time	Fall	Tf	$\theta X,  \theta Y = 0^{\circ}$	-	15	30	ms	Note 2	
	Тор	θY+		-	75	( -			
Viewing Angle	Bottom	θY-	CR ≥ 10	-	75	1	Dog	Note 4	
	Left	θX-		-	75	-	Deg.	NOLE 4	
	Right	θX+		-	75	-			
Contrast Ratio	Contrast Ratio			500	800	-	-	Note 3	
	White	Х		0.25	0.30	0.35	-		
	vvnite	Y		0.31	0.36	0.41			
	Red	Х	T- 0500	0.60	0.65	0.70			
Color of CIE Coordinate	Rea	Y	Ta = 25°C θX , θY = 0°	0.29	0.34	0.39		Note1	
(With B/L)	Green	Х	0,1,010	0.27	0.32	0.37		NOLET	
		Y		0.57	0.62	0.67			
	Blue	Х		0.09	0.14	0.19			
	Diue	Y		0.01	0.06	0.11			
Average Brightn	Average Brightness								
Pattern=White Display		IV	VBus=5.0V	300	350	-	cd/m <sup>2</sup>	Note1	
(With LCD) *1			PWM="High"						
Uniformity (With LCD) *2		۵B	(Duty=100%)	70	-	-	%	Note1	
	-								



#### Note1:

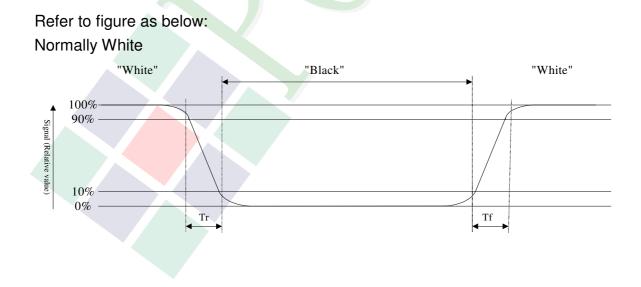
- $1 : \triangle B=B(min) / B(max) \times 100\%$
- 2 : Measurement Condition for Optical Characteristics:
  - a : Environment:  $25^{\circ}C \pm 5^{\circ}C / 60 \pm 20\%$  R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
  - b : Measurement Distance: 500  $\pm$  50  $\,$  mm  $\,$  , (0= 0°)
  - c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.
  - d: The uncertainty of the C.I.E coordinate measurement ±0.01 · Average Brightness ± 4%



To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

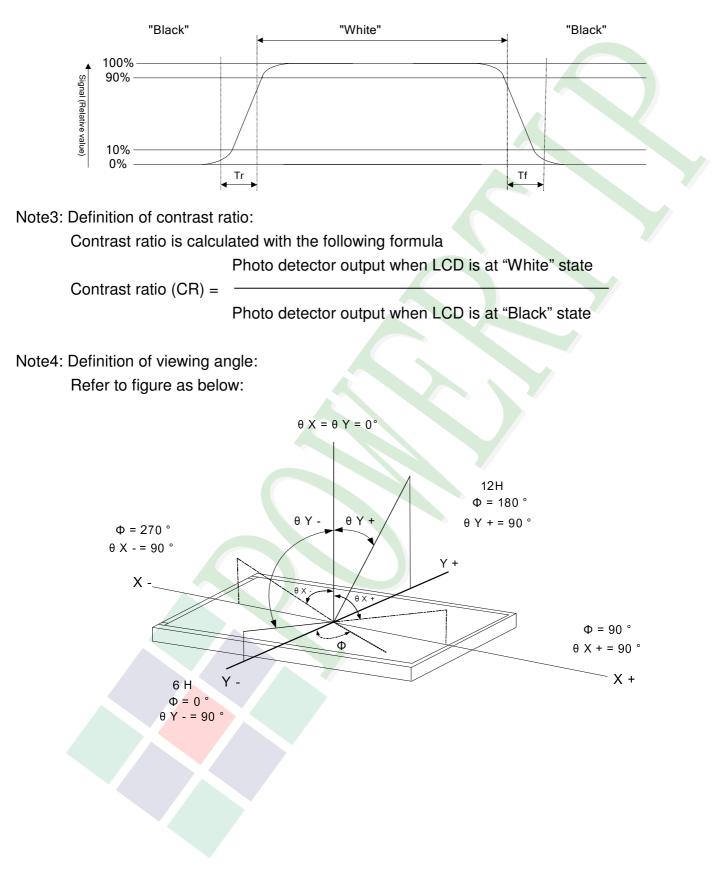
Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black"(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.





Normally Black





### **1.6 Backlight Characteristics**

#### Maximum Ratings

Item	Symbol	Min.	Max.	Unit	Remark
LED Forward Current	lF	20		mA	One LED
LED Reverse Voltage	VR	Ę	5	V	One LED

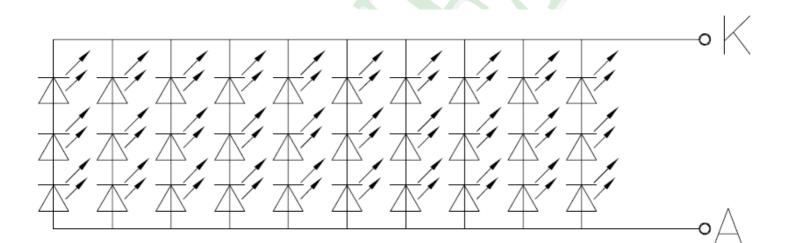
Electrical / Optical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark
LED Voltage	VL	I∟=200mA	8.7	9.6	10.2	V	Note1
LED Life Time	-		20000	-	-	hr	Note2

Note 1: The LED Supply Voltage is defined by the number of LED at Ta=25 °C.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at

Ta=25 °C and IL=200 mA. The LED life time could be decreased if operating IL is larger than 200 mA.





### 1.7 Touch Panel Characteristics

#### Features

Item	Standard Value
Touch Panel Size	7"
Touch Type	Projective Capacitive Touch Panel
Input Method	Finger / 5 Points Touch
Interface	l <sup>2</sup> C
I <sup>2</sup> C Address	0x38 (7-bit)

#### I<sup>2</sup>C Address

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0	1	1	1	0	0	0	R/W
	for \\/wito / 1	fax Daad					

Bit 0: 0 for Write / 1 for Read

#### **Mechanical Specifications**

Item	Standard Value	Unit
Viewing Area	154.88 (W) * 86.72 (L)	mm
Number of Sensing Channel	14 * 24	

#### Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Supply Voltage	TP_VDD	-	-0.3	+6.0	V
Operating Temperature	Тор	-	-20	+70	°C
Storage Temperature	T <sub>ST</sub>	-	-30	+80	°C
Storage Humidity	HD	Ta<25 ℃	-	90	%RH

#### **DC Electrical Characteristics**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	TP_VDD	-	2.8	3.3	3.6	V

### Touch Panel IC Read/Write description & Register Mapping

Reference: HYCON Touch Driver Porting Reference Guide.



### **1.8 HYCON I<sup>2</sup>C Sensitivity command:**

Address	Register description	R/W	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0x92	GAIN	R/W		Sens	itivity s	etting,	setting	ı range	: 05	

#### Application reference:

Register 0x92=02(Default)

without cover lens

#### Caution!

At different cover lens thickness can lead to touch Sensitivity changed (e.g. ghost-touches).

Therefore, the touch needs to be thoroughly tested in the target application.

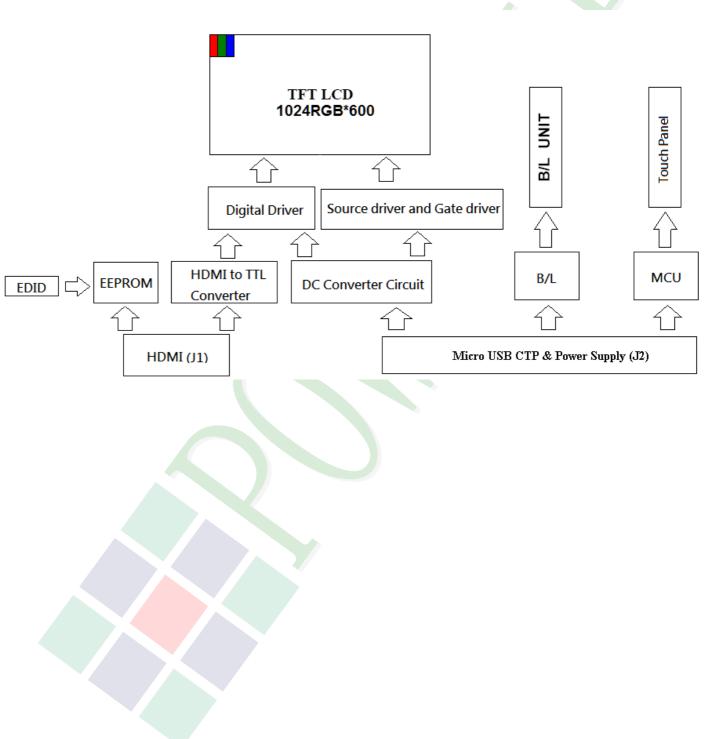
PTC application design suggestion is only for reference, please adjust based on your final design.



# 2. MODULE STRUCTURE

## 2.1 Counter Drawing

- 2.1.1 LCM Mechanical Diagram
  - \* See Appendix





## 2.2 Interface Pin Description (CN1)

## 2.2.1 (J1: HDMI 1.3 A type Interface)

Pin#	Name	Description
1	TX2+	TMDS Data 2+
2	TX2 Shield	TMDS Data 2 Shield
3	TX2–	TMDS Data 2-
4	TX1+	TMDS Data 1+
5	TX1 Shield	TMDS Data 1 Shield
6	TX1–	TMDS Data 1-
7	TX0+	TMDS Data 0+
8	TX0 Shield	TMDS Data 0 Shield
9	TX0–	TMDS Data 0-
10	TXC+	TMDS Clock+
11	TXC Shield	TMDS Clock Shield
12	TXC–	TMDS Clock-
13	CEC	CEC
14	NC	No Connection
15	SCL	Serial Clock for DDC
16	SDA	Serial Data for DDC
17	GND	Power Ground
18	V5V	+5V Power
19	Hot Plug Detect	Hot Plug Detect



### 2.2.2 (J2: Micro USB Capacitive Touch Panel & Power Supply Interface)

Pin#	Name	Description
1	VBus	VBus 4.75V-5.25V
2	D-	Data-
3	D+	Data+
4	ID	No Connection
5	GND	Power Ground.



### 2.3 HDMI Characteristics

#### 2.3.1 Signal DC&AC Characteristics

#### DC ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP MAX	UNIT
VID	Analog input differential voltage <sup>(1)</sup>		75	1200	mV
VIC	Analog input common-mode voltage <sup>(1)</sup>		$AV_{DD} - 300$	AV <sub>DD</sub> – 37	mV
V <sub>I(OC)</sub>	Open-circuit analog input voltage		AV <sub>DD</sub> - 10	AV <sub>DD</sub> + 10	mV
I <sub>DD(2PIX)</sub>	Normal 2-pix/clock power supply current (2)	ODCK = 82.5 MHz, 2-pix/clock		370	mA
I <sub>PD</sub>	Power-down current (3)	PD = low		10	mA
I <sub>PDO</sub>	Output drive power-down current <sup>(3)</sup>	PDO = low		35	mA

(1) Specified as dc characteristic with no overshoot or undershoot

(2) Alternating 2-pixel black/2-pixel white pattern. ST = high, STAG = high, QE[23:0] and QO[23:0] CL = 10 pF.

(3) Analog inputs are open circuit (transmitter is disconnected from TFP401/401A).

#### AC ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VID(2)	Differential input sensitivity <sup>(1)</sup>		150		1560	mV <sub>p-p</sub>
t <sub>ps</sub>	Analog input intra-pair (+ to –) differential skew <sup>(2)</sup>				0.4	t <sub>bit</sub> <sup>(3)</sup>
t <sub>ccs</sub>	Analog input inter-pair or channel-to-channel skew <sup>(2)</sup>				1	t <sub>pix</sub> <sup>(4)</sup>
t <sub>ijit</sub>	Worst-case differential input clock jitter tolerance <sup>(2)(5)</sup>		50			ps
+	Fall time of data and control signals <sup>(6)(7)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	ns
t <sub>f1</sub>		ST = high, C <sub>L</sub> = 10 pF			1.9	115
+	Rise time of data and control signals <sup>(6)(7)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	ns
<b>Ļ</b> 1	Rise time of data and control signals (A)	ST = high, C <sub>L</sub> = 10 pF			1.9	115
	Rise time of ODCK clock <sup>(6)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	
t <sub>r2</sub>	Rise time of ODCK dock (*)	ST = high, C <sub>L</sub> = 10 pF			1.9	ns
	Fall time of ODCK clock <sup>(6)</sup>	ST = low, C <sub>L</sub> = 5 pF			2.4	
t <sub>f2</sub>	Fail time of ODCK clock**	ST = high, C <sub>L</sub> = 10 pF			1.9	ns
		1 pixel/clock, PIXS = low, OCK_INV = low	1.8			
t <sub>su1</sub>	Setup time, data and control signal to falling edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	3.8			ns
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	0.7			
		1 pixel/clock, PIXS = low, OCK_INV = low	0.6			
t <sub>h1</sub>	Hold time, data and control signal to falling edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = low	2.5			ns
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = low	2.9			

(1) Specified as ac parameter to include sensitivity to overshoot, undershoot and reflection.

(2) By characterization

(3) t<sub>bit</sub> is 1/10 the pixel time, t<sub>pix</sub>

(4) t<sub>pix</sub> is the pixel time defined as the period of the RxC input clock. The period of ODCK is equal to t<sub>pix</sub> in 1-pixel/clock mode or 2t<sub>pix</sub> when in 2-pixel/clock mode.

(5) Measured differentially at 50% crossing using ODCK output clock as trigger

(6) Rise and fall times measured as time between 20% and 80% of signal amplitude.

(7) Data and control signals are QE[23:0], QO[23:0], DE, HSYNC, VSYNC. and CTL[3:1].



#### AC ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
		1 pixel/clock, PIXS = low, OCK_INV = high	2.1				
t <sub>su2</sub>	Setup time, data and control signal to rising edge of ODCK	2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	4			ns	
		2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	1.5				
		1 pixel/clock, PIXS = low, OCK_INV = high	0.5				
t <sub>h2</sub>	Hold time, data and control signal to rising edge of ODCK	2 pixel and STAG, PIXS = high, STAG = low, OCK_INV = high	2.4			ns	
		2 pixel/clock, PIXS = high, STAG = high, OCK_INV = high	2.1	2.1			
	ODOK framuenau	PIX = low (1-PIX/CLK)	25		165	MHz	
fodck	ODCK frequency	PIX = high (2-PIX/CLK)	12.5		82.5	MHZ	
	ODCK duty-cycle		40%	50%	60%		
t <sub>pd(PDL)</sub>	Propagation delay time from PD low to Hi-Z outputs				9	ns	
t <sub>pd(PDOL)</sub>	Propagation delay time from PDO low to Hi-Z outputs				9	ns	
t <sub>t(HSC)</sub>	Transition time between DE transition to SCDT $\ensuremath{low}^{(8)}$			1e6		t <sub>pix</sub>	
t <sub>t(FSC)</sub>	Transition time between DE transition to SCDT high <sup>(8)</sup>			1600		t <sub>pix</sub>	
t <sub>d(st)</sub>	Delay time, ODCK latching edge to QE[23:0] data output	STAG = low, PIXS = high		0.25		t <sub>pix</sub>	

(8) Link active or inactive is determined by amount of time detected between DE transitions. SCDT indicates link activity.



### 2.3.2 Parameter Measurement Information

#### PARAMETER MEASUREMENT INFORMATION

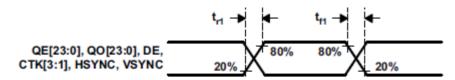


Figure 1. Rise and Fall Times of Data and Control Signals

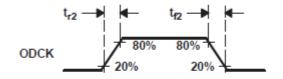


Figure 2. Rise and Fall Times of ODCK

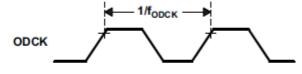


Figure 3. ODCK Frequency

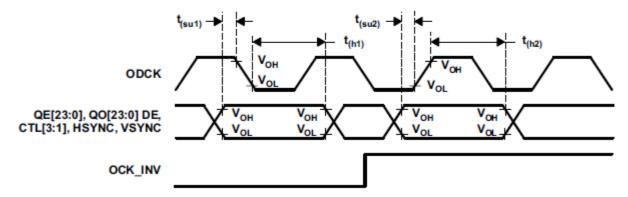
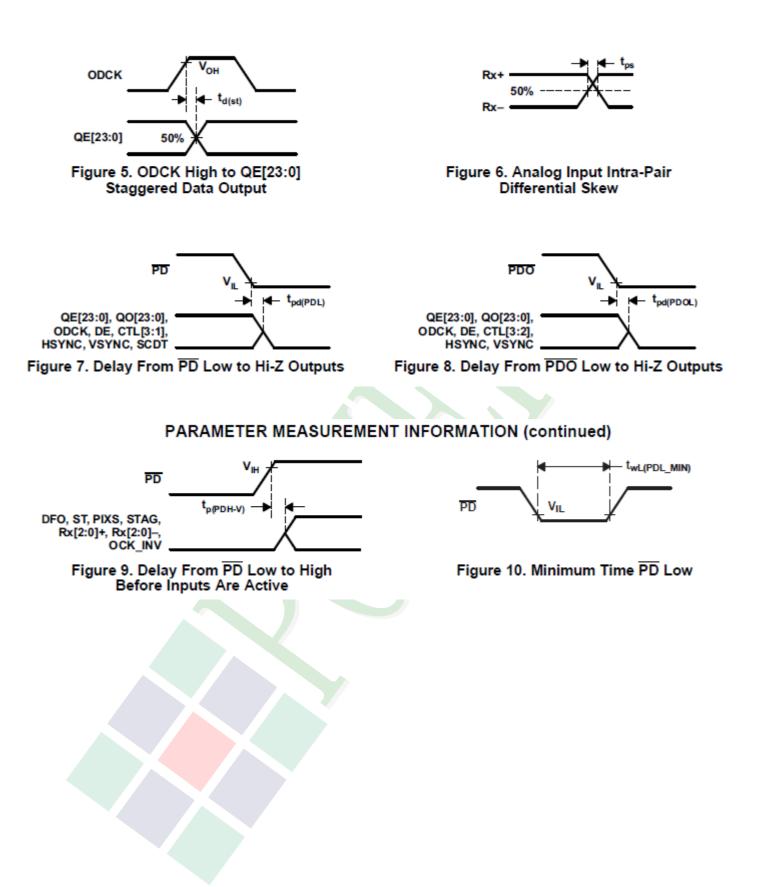


Figure 4. Data Setup and Hold Times to Rising and Falling Edges of ODCK









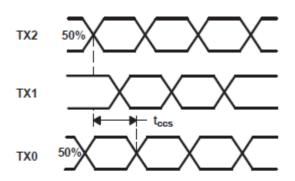


Figure 11. Analog Input Channel-to-Channel Skew

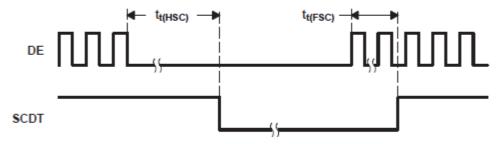


Figure 12. Time Between DE Transitions to SCDT Low and SCDT High

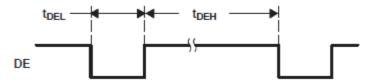


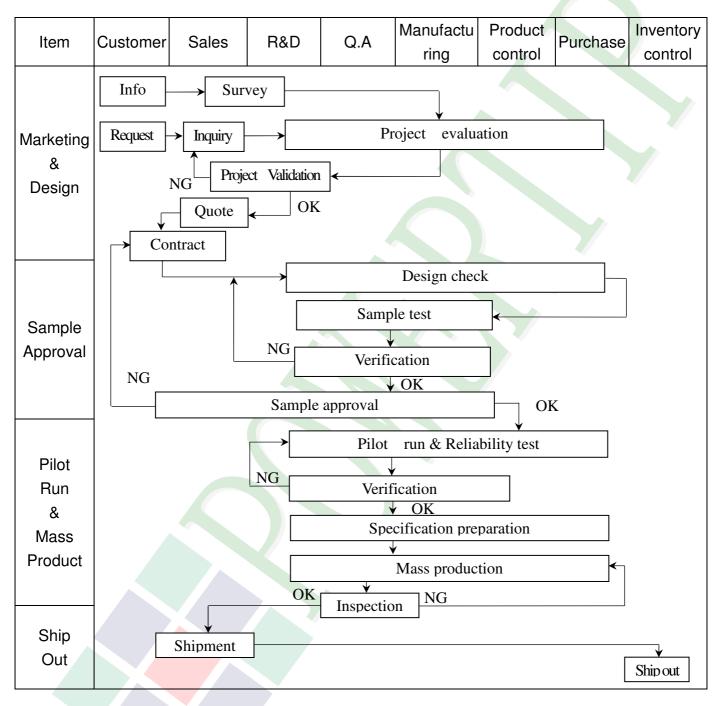
Figure 13. Minimum DE Low and Maximum DE High

#### DETAILED DESCRIPTION



# **3. QUALITY ASSURANCE SYSTEM**

## 3.1 Quality Assurance Flow Chart





Item	Customer	Sales	R&D	Q.A	Manufact uring	Product control	Purchase	Inventory control
Sales Service	Info	Claim	[	Trackin	Failure an Corrective			
	1. ISO 900 3. Equipme 5. Standard	ent calibrati	ion	4	Process in Education		nt proposal ing Activitie	es

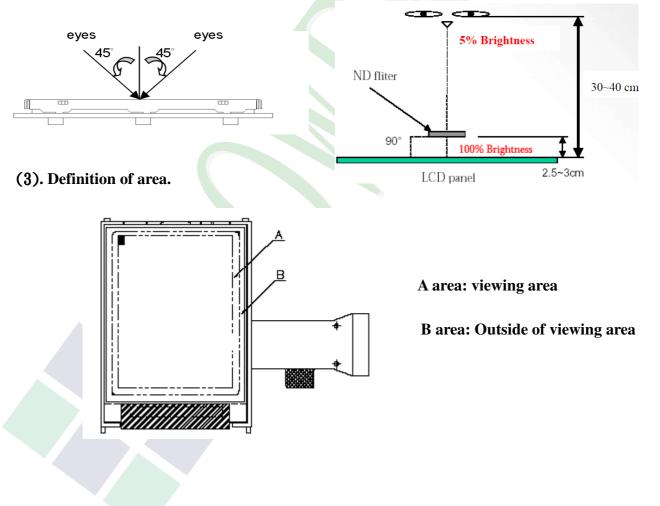
POWERTIP

## **3.2. Inspection Specification**

- ◆Scope: The document shall be applied to TFT-LCD Module for 3. 5" -15″ (Ver.B01).
- ◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

**•**Equipment: Gauge, MIL-STD, Powertip Tester, Sample

- Defect Level: Major Defect AQL: 0. 4; Minor Defect AQL: 1. 5
- **OUT Going Defect Level: Sampling.**
- **♦**Standard of the product appearance test:
  - a. Manner of appearance test:
  - (1). The test best be under 20W×2 fluorescent light(about 300lux ~500lux)
    - , and distance of view must be at 30~40 cm.
  - (2). The test direction is base on about around 45° of vertical line.



(4). Standard of inspection : (Unit : mm)



NO∉	Item₊⊃		Criterion. <sup>2</sup>					
			art nun luction.		with work order of	Major		
01₽	Product condition.	1. 2 Mixed product types.						
		1. 3 Asser	1. 3 Assembled in inverse direction.40					
02₽	Quantity₽	2. 1The q	luantity	is inconsistent with	work order of productio	on.∉ Major		
03₽	Outline dimension∉	3. 1Produ diagr		ension and structu	re must conform to stru	ucture Major		
		4. 1 Missi	ing line	character and icon.	ς <sub>φ</sub>	Major		
		4. 2 No fu	inction	or no display.↩		Majoı		
	Electrical Testing.	4. 3 Display malfunction. 🗸						
04₽		4.4 LCD viewing angle defect.↔						
		4. 5 Curr	ent con	sumption exceeds p	roduct specifications.↩	Majoı		
				-	% ND filter at 50% Gray ng angle of 90 degree.4	4 Minor		
		نه ا		Item₽	Acceptance (Q'ty)	1		
				Bright Dot.	<u>≦</u> 4₀ ↔	i		
	Dot defect₊≀		Dot	Dark Dot₊	چ 5₽ ₽	I		
	ц. С	I	Defect₊	Joint Dot 🤞	ب نۇ	I		
05₽	(Bright dot,↩ Dark dot) ↩			Total₽	<u>≨</u> 7₽ ₽	Minor		
	نه د <b>-display</b> نه	5. 2 It is d	defined	blue scree as dot defect if defe	ct area >1/2 dot.↓	n and		
				e between two dot de hat can not be seen	through 5% ND filter.↓			



NO₽	Item↩	<b>Criterion</b> ₄ <sup>3</sup>						Level	
	ተ ተ ተ ተ			Non-display			nce (Q'ty)≓ B area		
	ب Black or white Dot, scratch,⊷		0.25			Ignore इल्	<i>ب</i> د		
	contamination.		$\Phi > 0.$		.50₽	<b>0</b> ₊⊃	- Ignor	₽¢ <sup>-</sup>	
	ب ⊀Round type		•	Total₽		5₽		¢,	
	$ \xrightarrow{\mathbf{x}_{i}} \underbrace{\underbrace{\mathbf{x}_{i}}_{\mathbf{x}_{i}}}_{\mathbf{x}_{i}} \underbrace{\mathbf{x}_{i}}_{\mathbf{x}_{i}} \underbrace{\mathbf{x}_{i}} $	ب ا		n-display o Length			Acceptanc	æ (Q'ty)∉.	
06₽	↓	mo	dule size₽	(Ľ),₀	w	idth (W)¢	A area₽		
	$\Phi = (x+y)/2 e^{-t}$			¢	0.00	W ≤ 0.03↔	Ignore↩		Minor
	* (x+j)/2*			L ≦10.0∉ L ≦5.0∉		<w 0.05¢<br="" ≦=""><w 0.10¢<="" td="" ≦=""><td>4↩ 2↩</td><td>4</td><td></td></w></w>	4↩ 2↩	4	
	Line type≁	3.5"	to less 9"∉	+2	0.05	<u>√ () ⊴</u> 0.10+ W >0.10+	As round type₊	Ignore	
	/ ¥ ₩+				Total	<b>ب</b>	5₽	م I	
				+ <sup>2</sup>		W ≤ 0.05 <sup>↓</sup> Ignore <sup>↓</sup>		сь С	
	L <sup>4</sup>	07	• 9" to 15".	L ≦10.0¢	0.05	<w <u="">≦ 0.10₽</w>	5.₽	₽ ₽	
		<b>_</b>		+2	Total	W >0.10∉	As round type↔ 5↔		
					1014			11	
		ب ر	Dimension	(diameter:	<b>Φ)</b> ₀		nce (Q'ty)≓		
				-	-	A area₽	B ar	<b>ea</b> ຊີ	
	Polarizer↩		0.25 <	$\Phi \leq 0.25$ $\Phi \leq 0.50$		Ignore₽ 4₽	_	¢.	
07⊷	Bubble			Φ <u>≦</u> 0.80		1,0	 Igno	re e	Minor
				Φ >0.80		0⇔0		₽	
			1	ſotal₽		5₽		ę	
									-

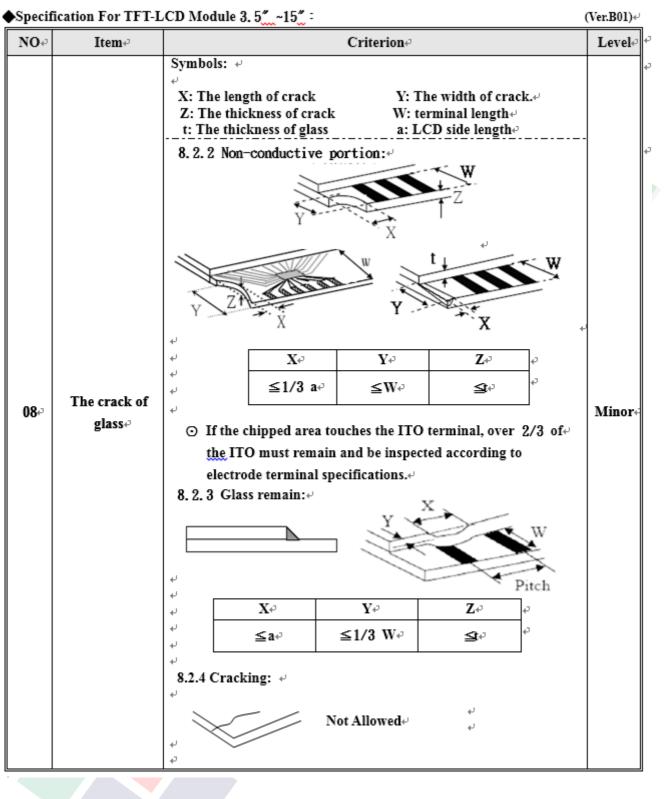


Specifi	ication For TFT-LCD N	/Iodule 3. 515 =	(Ver.B01)↔		
NO₄⊃	Item₽	<b>Criterion</b> + <sup>3</sup>			
		با Symbols : با با X: The length of crack Y: The width of crack. Z: The thickness of crack W: terminal length t: The thickness of glass a: LCD side length با			
		8.1 General glass chip:~			
		8.1.1 Chip on panel surface and crack between panels:+/			
		$ \begin{array}{c}                                     $			
08₄⊃	The crack of glass₊ <sup>3</sup>	$ \begin{array}{c} e^{iJ} \\ e^{i$	Minor↔		
		له ا			
		$\begin{array}{c} \downarrow \\ \downarrow $			
		<sup>4</sup> <sup>4</sup> X., Y., Z., <sup>4</sup>			
		$ \leq a^{2} \qquad \begin{array}{c} Crack \ can't \ enter \\ \bullet \\ \bullet \end{array} \qquad \qquad \leq 1/2 \ t^{2} \qquad \qquad$			
		$\leq a^{\varphi} \qquad \begin{array}{c} \text{Crack can't exceed the} \\ \text{half of SP width.} \end{array} \qquad 1/2 \ t < Z \leq 2 \ t^{\varphi} \end{array}^{\varphi}$			



$08^{\circ}$ The crack of glass <sup>2</sup> $8.2 \text{ Protrusion over terminal :**} X \cdot Y \cdot Y \cdot Z \cdot Y \cdot Z \cdot Z \cdot Z \cdot Z \cdot Z \cdot Z \cdot $	<b>0</b> ₽	Item₽	<b>Criterion</b> ₊ <sup>2</sup>				
08° The crack of glasso 8. 2 Protrusion over terminal: " 8. 2.1 Chip on electrode pad: " W View Ye Ze W View Save Save Save Save Save Save Save Save			ب       X: The length of crack       Y: The width of crack.         Z: The thickness of crack       W: terminal length         t: The thickness of glass       a: LCD side length				
08.0 The crack of glasso $\frac{e^2}{2}$ $\frac{\leq 1/5 \ a^{\circ}}{2}$ $\frac{Crack \ can't \ enter viewing \ area^{\circ}}{2}$ $Z \le 1/2 \ t^{\circ}$ $\frac{\leq 1/5 \ a^{\circ}}{2}$ $\frac{Crack \ can't \ exceed \ the half \ of \ SP \ width \ o^{\circ}}{2}$ $1/2 \ t < Z \le 2 \ t^{\circ}$ $8.2 \ Protrusion \ over \ terminal: \ over \ termi$			$ \begin{array}{c}                                     $				
08° The crack of glass?			$\stackrel{\text{\tiny 4}}{\underset{\text{\tiny 4}}{}} \mathbf{X}_{.7} \qquad \mathbf{Y}_{.7} \qquad \mathbf{Z}_{.7} \qquad \stackrel{\text{\tiny 4}}{\underset{\text{\tiny 4}}{}}$				
080 The crack of glass $\frac{e^{\frac{1}{2}} \leq 1/5 \ a^{e^{\frac{1}{2}}}}{8.2 \ Protrusion over terminal: e^{\frac{1}{2}}}$ 8.2 Protrusion over terminal: $e^{\frac{1}{2}}$ 8.2.1 Chip on electrode pad: $e^{\frac{1}{2}}$ $\frac{1}{2} = \frac{1}{2} = \frac{1}{$			$ \leq 1/5 a_{\rm e} $ Crack can't enter $Z \leq 1/2 t_{\rm e}$				
8.2.1 Chip on electrode pad: $V = \frac{1}{X_{e^2}}$ $X = \frac{1}{X_{e^2}}$							
8.2.1 Chip on electrode pad: $V = X^{e^{2}}$ $X = X^{e^{2}}$	08₽	The crack of glass					
$\frac{1}{2} \frac{1}{2} \frac{1}$		8	0.2 Hotrusion over terminal.				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $							
$\begin{array}{ c c c c c c c c c } \hline & & & & & & & & & & & & & & & & & & $			A COLORADO				
Front $\leq a^{\varphi}$ $\leq 1/2 W^{\varphi}$ $\leq t^{\varphi}$ Back $\leq a^{\varphi}$ $\leq a^{\varphi}$ $\leq V^{\varphi}$			$\psi$ $\mathbf{A}\psi$ $\mathbf{Y}\psi$ $\mathbf{Z}\psi$ $\psi$				
$\begin{array}{c c c c c c c c c } Back^{\wp} & \leq a^{\wp} & \leq W^{\wp} & \leq 1/2 t^{\wp} \end{array}^{\wp} \end{array}$			<b>Front</b> $\varphi$ $\leq a\varphi$ $\leq 1/2 W\varphi$ $\leq t\varphi \varphi$				
			<b>Back</b> $\varphi$ $\leq a\varphi$ $\leq W\varphi$ $\leq 1/2 t\varphi \varphi$				
.1							







#### ◆Specification For TFT-LCD Module 3. 5″~15″:

Specification For TFT-LCD Module 3. 5 <sup>m</sup> / <sub>2</sub> ~15 <sup>m</sup> / <sub>2</sub> :					
• NO <sub>4</sub> 2	Item↩	Criterion			
	Backlight elements+ <sup>3</sup>	9. 1 Backlight can't work normally.↔	Major↔		
09⊷		9. 2 Backlight doesn't light or color is wrong.↔	Major↔		
		9. 3 Illumination source flickers when lit.42	Major≁		
	General appearance43	10. 1Pin type 、 quantity 、 dimension must match type in structure diagram.↔	Major₊		
		10. 2 No short circuits in components on PCB or FPC.	Major≁		
		10.3 Parts on PCB or FPC must be: no wrong parts, missing parts or excess parts.43	4 Major¢		
10~		10. 4 Product packaging must the same as specified on packaging specification sheet.43	Minor≁		
		10. 5 The folding and peeled off in polarizer are not acceptable.↔	Minor₊³		
		10. 6 The PCB or FPC between B/L assembled distance(PCB or ↔ FPC ) is ≤1.5 mm.↔	Minor↔		



## 4. RELIABILITY TEST

4.1 Reliability Test Condition

(Ver.B01)

4.1						
NO.	TEST ITEM	TEST CONDITION				
1	High Temperature Storage Test	Keep in +80 ±5℃ 240 hrs				
2	Low Temperature Storage Test	Keep in -30 ±5℃ 240 hrs				
3	High Temperature / High Humidity Storage Test	Keep in +60 ℃ / 90% R.H duration for 240 hrs (Excluding the polarizer)				
4	Temperature Cycling Storage Test	$-30^{\circ}C \rightarrow +25^{\circ}C \rightarrow +80^{\circ}C \rightarrow +25^{\circ}C$ $(30 \text{mins})  (5 \text{mins})  (30 \text{mins})  (5 \text{mins})$ $20 \text{ Cycle}$				
5	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarit 1.Temperature ambiance 2.Humidity relative : 30% 3.Energy Storage Capacit 4.Discharge Resistance(Ro 5.Discharge, mode of open Single Discharge (time b (Tolerance if the output v	ty +/- : $15^{\circ} \sim 33$ $6 \sim 60\%$ tance(Cs+( d) : $330\Omega$ ration : between su	Cd):150pF±10% ±10% accessive discharges at	nrity +/-	
6	Vibration Test (Packaged)	<ul> <li>1.Sine wave 10~55 Hz frequency (1 min/sweep)</li> <li>2.The amplitude of vibration :1.5 mm</li> <li>3.Each direction (X \ Y \ Z) duration for 2 Hrs</li> </ul>				
7	Drop Test (Packaged)	45.4 ~ 90.8 ~ Over	45. 4 90. 8 454 454	Drop Height (cm) 122 76 61 46		
	sult Evaluation Criteria :	Drop Direction : <b>%</b> 1 corne	er / 3 edge	s / b sides each ltime		

**OResult Evaluation Criteria :** 

Under the display quality test conditions with normal operations with normal operation state. Do not change these conditions as such changes may affect practical display function.

(Normal operation state) Temperature: +20~30°C Humidity: 50~70% Atmospheric pressure: 86~106Kpa



# **5. PRECAUTION RELATING PRODUCT HANDLING**

### 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

### 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM
- 5.2.10 Caution!( LCM products with Capacitive Touch Panel)

Strong EMI-sources such as switch-mode power supplies (SMPS) can lead to touch malfunction (e.g. ghost-touches).

Therefore, the touch needs to be thoroughly tested inside the target application.

5.2.11 CAUTION: Continuously displaying same static image will result in high possibility of image sticking/image burn-in effect due to TFT panel characteristic.

### 5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}C \pm 5^{\circ}C$  and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

## 5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

